

L Number	Hits	Search Text	DB	Time stamp
7	25	257/784.ccls. and (copper adj2 pad)	USPAT	2004/01/08 23:47
8	20	(257/784.ccls. and (copper adj2 pad)) and aluminum	USPAT	2004/01/08 23:59
9	43832	semiconductor and (aluminum adj3 buried copper)	USPAT	2004/01/09 00:00
10	0	semiconductor and (aluminum adj3 buried adj2 copper)	USPAT	2004/01/09 00:00
11	0	semiconductor and (aluminum adj3 buried adj3 copper)	USPAT	2004/01/09 00:01
12	0	pad and (aluminum adj3 buried adj3 copper)	USPAT	2004/01/09 00:01
13	3534	pad and (aluminum adj2 copper)	USPAT	2004/01/09 00:01
14	2316	(pad and (aluminum adj2 copper)) and semiconductor	USPAT	2004/01/09 00:01
15	584	(257/762).CCLS.	USPAT	2004/01/09 00:02
16	14194	((257/762).CCLS.) aluminum and copper and pad	USPAT	2004/01/09 00:02
17	101	((257/762).CCLS.) and aluminum and copper and pad	USPAT	2004/01/09 00:02